

## 20V N-Channel Mosfet

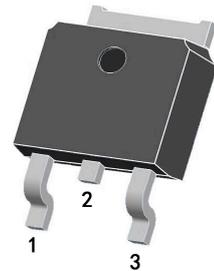
### FEATURES

- $R_{DS(ON)} < 4m\Omega @ V_{GS} = 4.5V$
- $R_{DS(ON)} < 6m\Omega @ V_{GS} = 2.5V$

### APPLICATIONS

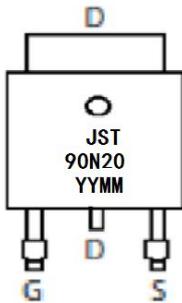
- Load Switch
- PWM Application
- Power management

### TO-252



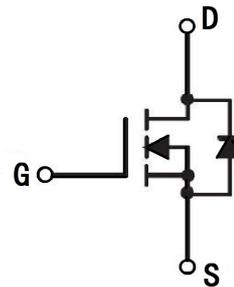
1: G  
2: D  
3: S

### MARKING



YYMM:Date Code(year&month)

### N-CHANNEL MOSFET



Maximum ratings ( $T_C=25^\circ C$  unless otherwise noted)

Symbol	Parameter	Max.	Units	
$V_{DSS}$	Drain-Source Voltage	20	V	
$V_{GSS}$	Gate-Source Voltage	$\pm 12$	V	
$I_D$	Continuous Drain Current	$T_C = 25^\circ C$	90	A
		$T_C = 100^\circ C$	59	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	360	A	
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>	110	mJ	
$P_D$	Power Dissipation	$T_C = 25^\circ C$	81	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.85	$^\circ C/W$	
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +175	$^\circ C$	

## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	20	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V	-	-	1	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = 250μA	0.4	0.7	1.1	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance <small>note3</small>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 30A	-	2.8	4	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 20A		4	6	
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	3200	-	pF
C <sub>oss</sub>	Output Capacitance		-	460	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	445	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V, I <sub>D</sub> = 17A, V <sub>GS</sub> = 4.5V	-	48	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	3.6	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	19	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> = 15V, I <sub>D</sub> = 17A, R <sub>G</sub> = 1.8Ω, V <sub>GS</sub> = 4.5V	-	9.7	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	37	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	63	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	52	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	90	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	360	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>SD</sub> = 30A, T <sub>J</sub> = 25°C	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> = 25°C, I <sub>F</sub> = 30A,	-	23	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt = 100A/μs	-	10	-	nC

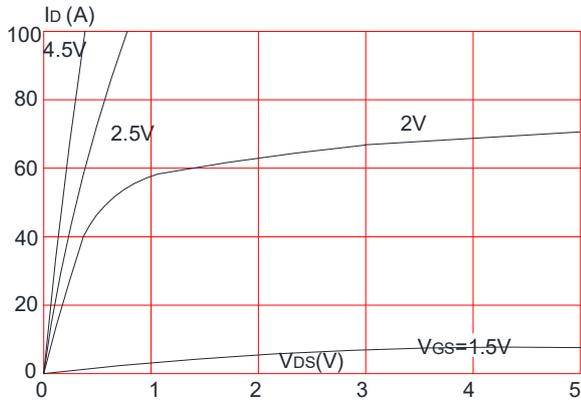
Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T<sub>J</sub> = 25°C, V<sub>DD</sub> = 15V, V<sub>G</sub> = 4.5V, R<sub>G</sub> = 25Ω, L = 0.5mH, I<sub>AS</sub> = 21A

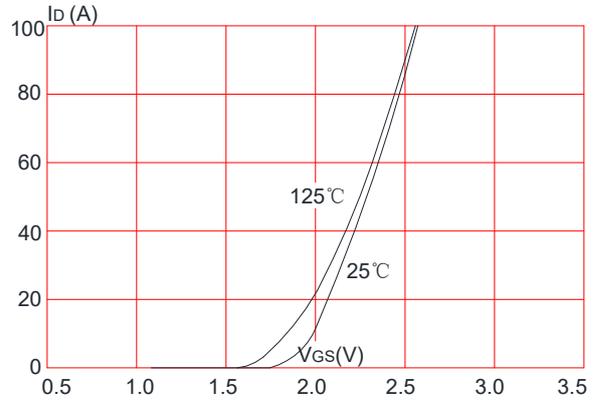
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%

## Typical Characteristics

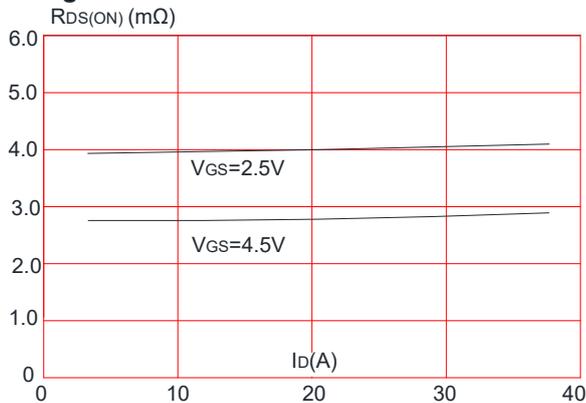
**Figure 1: Output Characteristics**



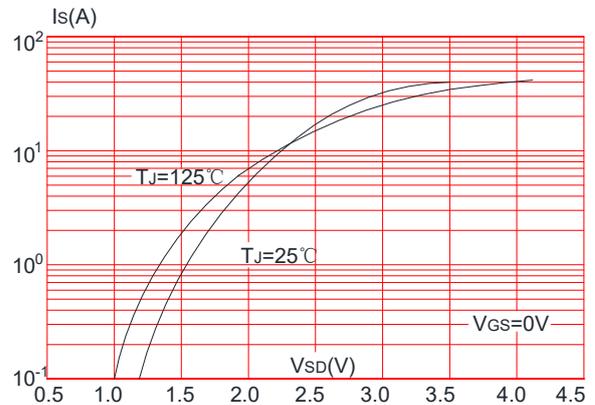
**Figure 2: Typical Transfer Characteristics**



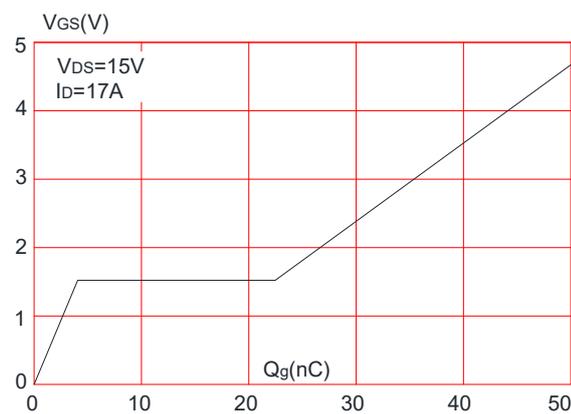
**Figure 3: On-resistance vs. Drain Current**



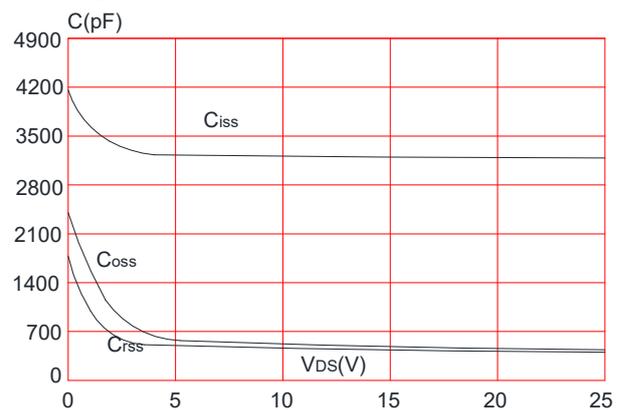
**Figure 4: Body Diode Characteristics**



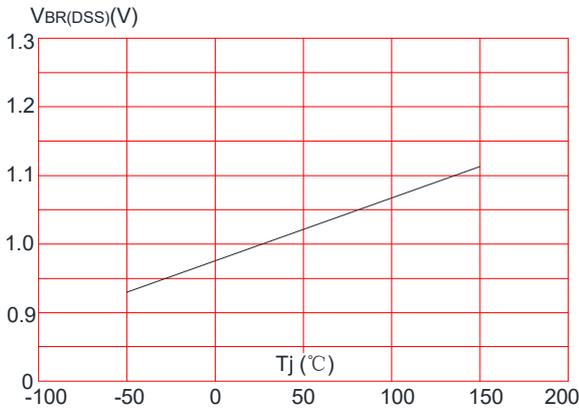
**Figure 5: Gate Charge Characteristics**



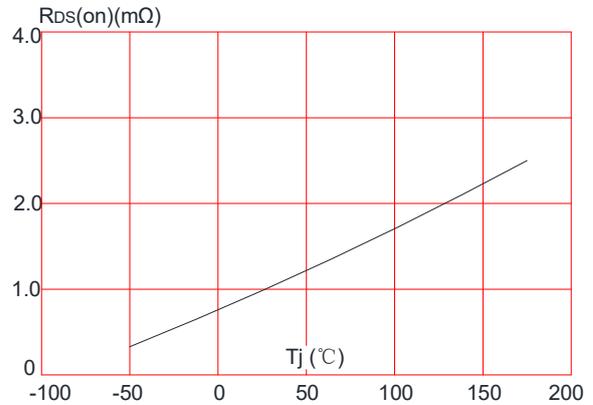
**Figure 6: Capacitance Characteristics**



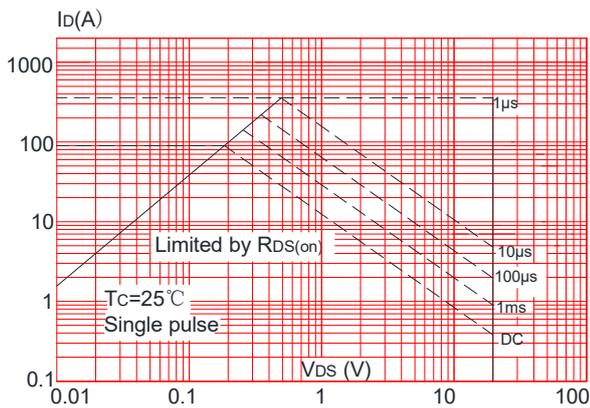
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



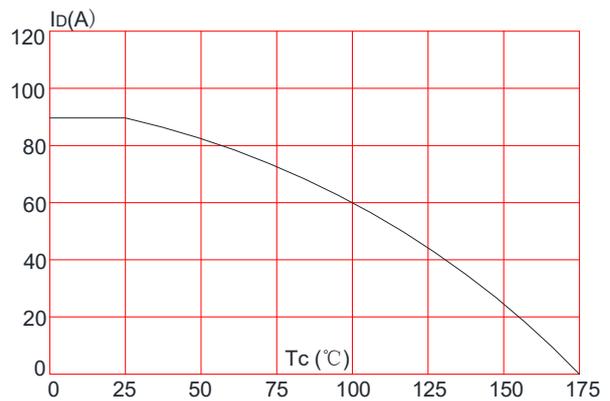
**Figure 8:** Normalized on Resistance vs. Junction Temperature



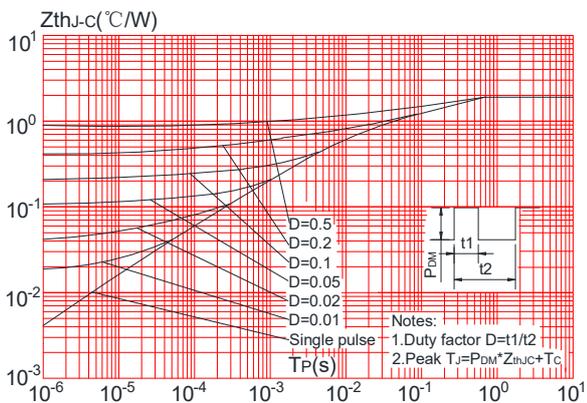
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



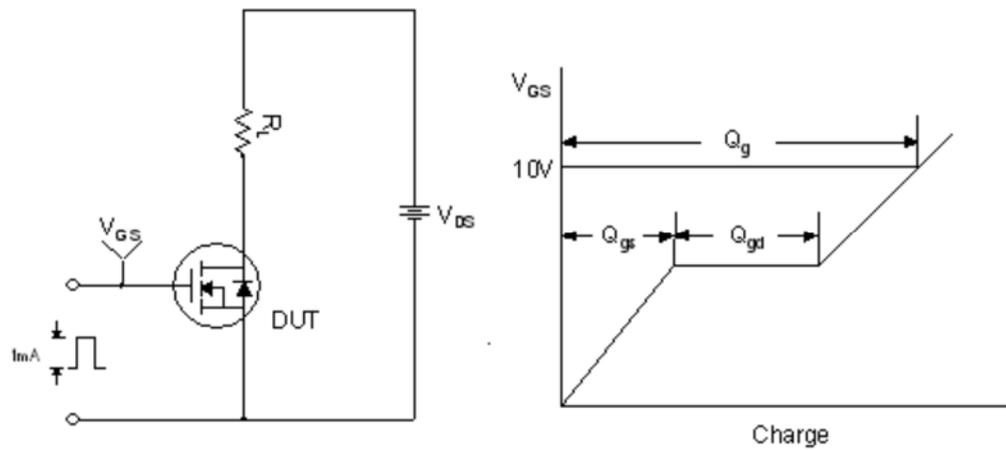


Figure 1. Gate Charge Test Circuit & Waveform

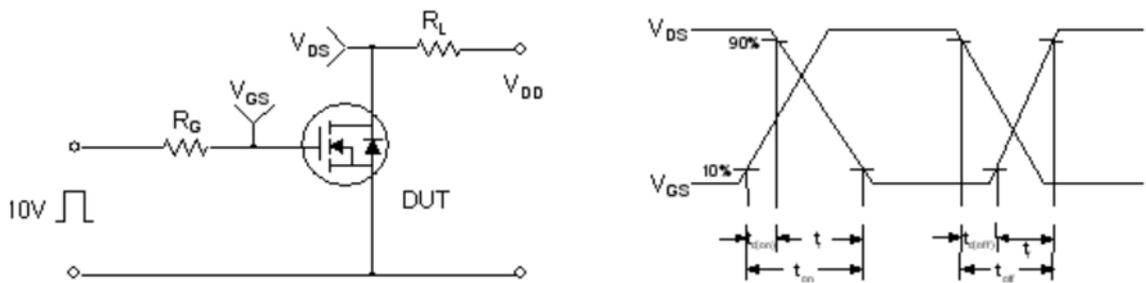


Figure 2. Resistive Switching Test Circuit & Waveforms

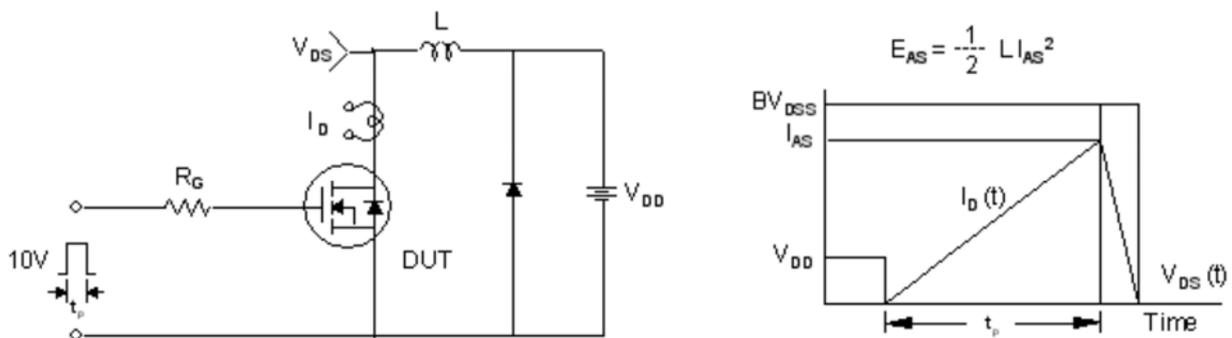
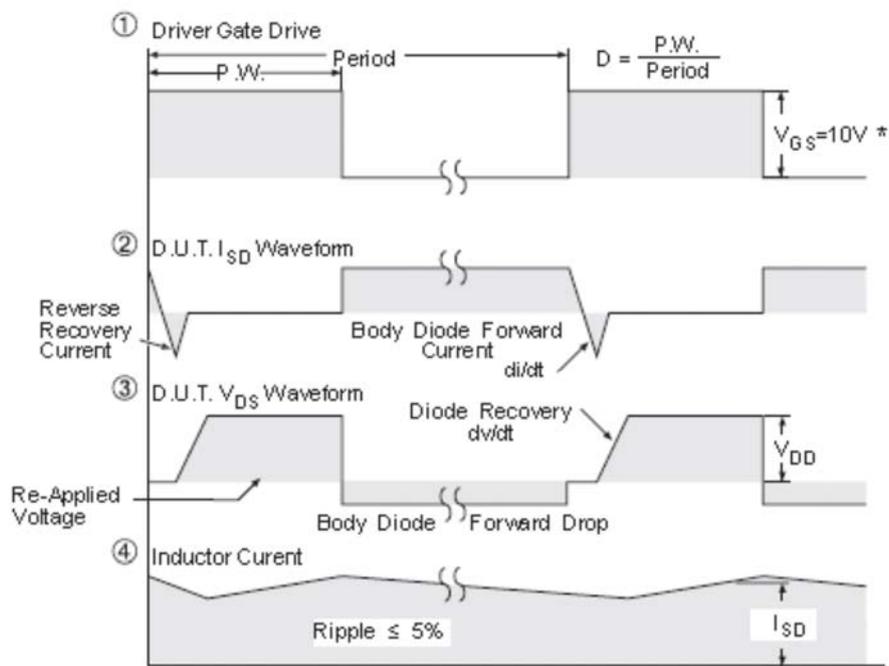
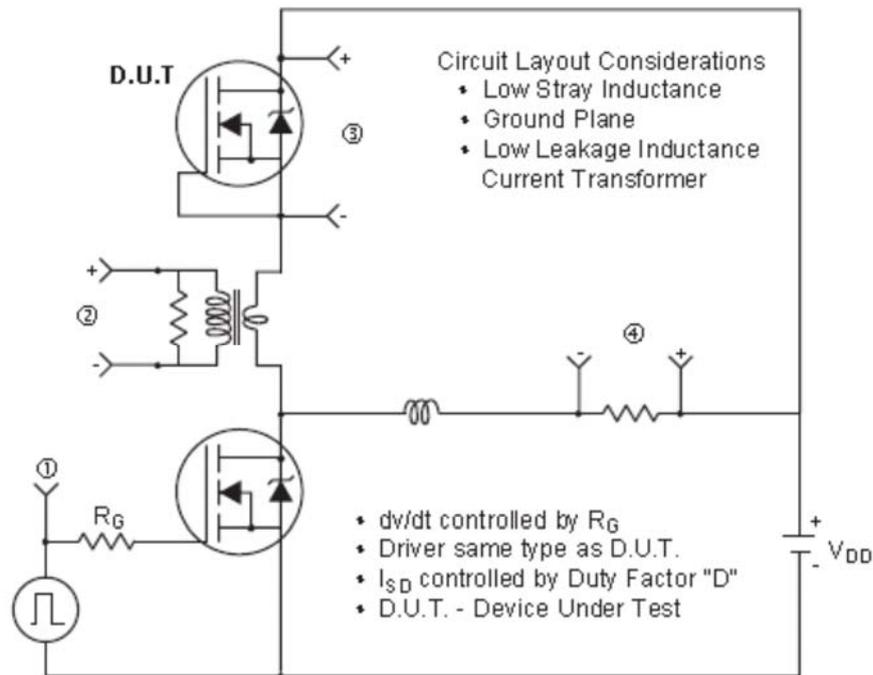


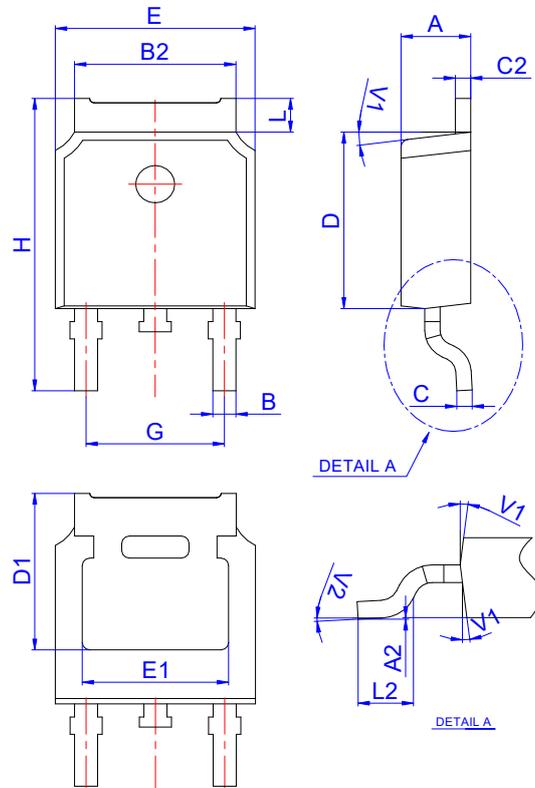
Figure 3. Unclamped Inductive Switching Test Circuit & Waveforms



\*  $V_{GS} = 5V$  for Logic Level Devices

Figure 4. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms (For N-channel)

## TO-252 PACKAGE OUTLINE DRAWING



Symbols	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°